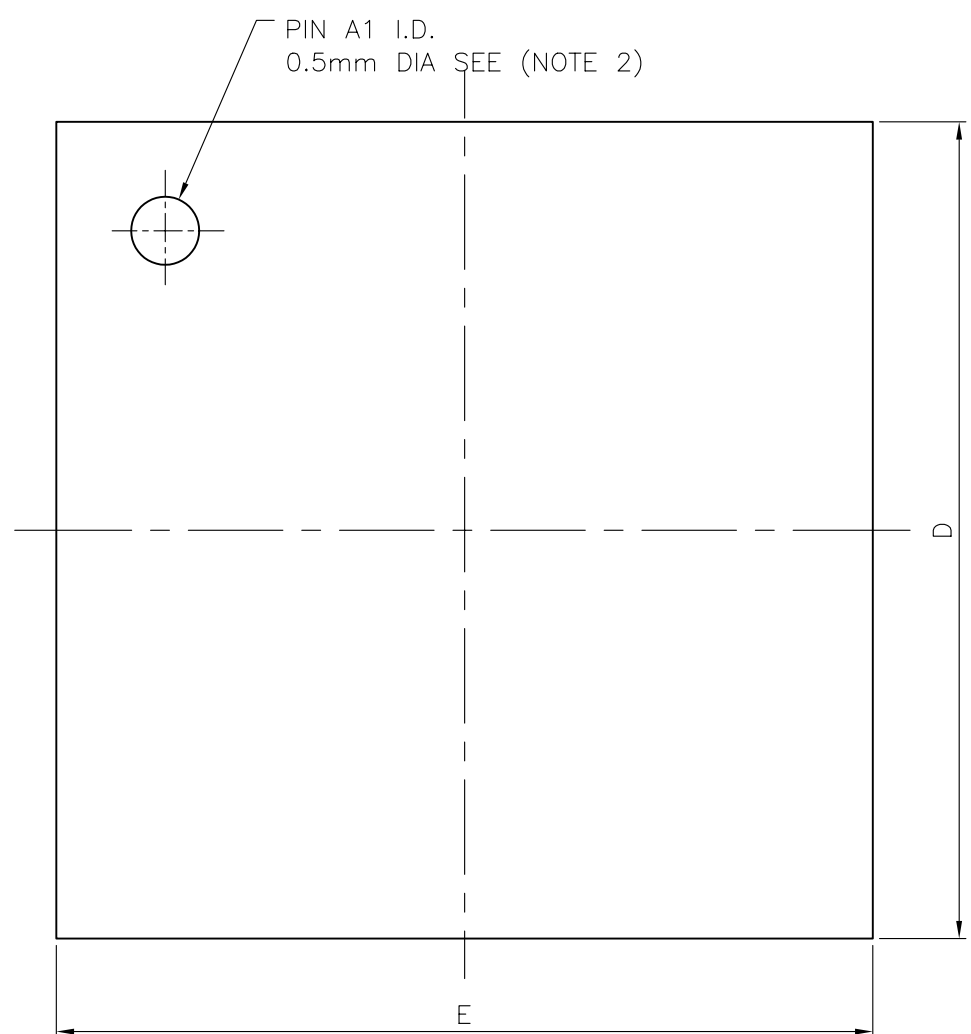
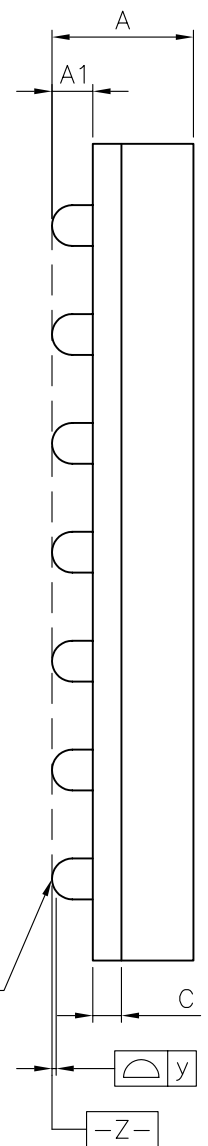
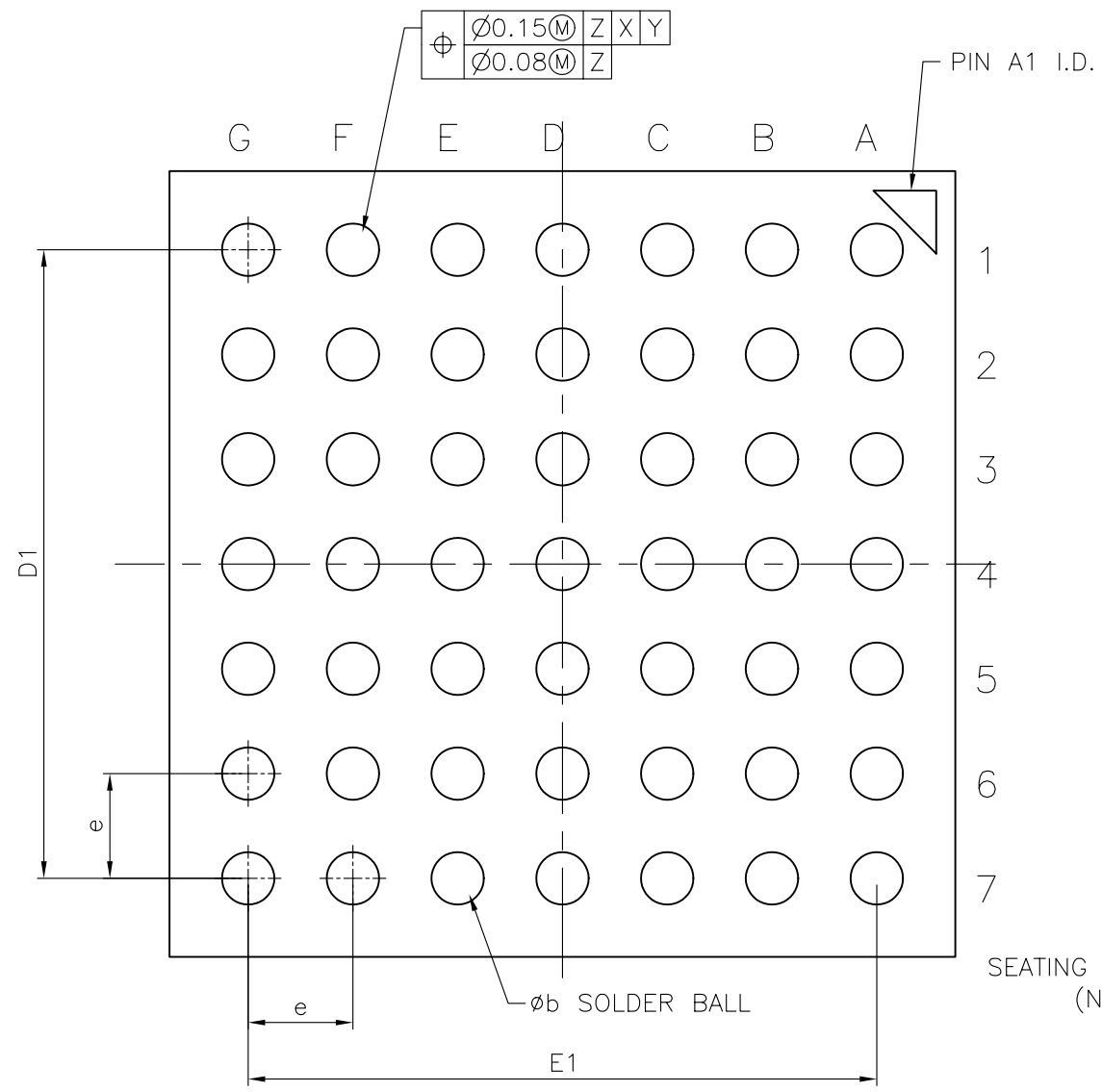


BOTTOM SIDE BOTTOM VIEW

TOP SIDE TOP VIEW



- NOTE :
1. ALL DIMENSION ARE IN MILLIMETERS.
 2. PIN A1 ID. TO BE MARKED BY LASER.
 3. PRIMARY DATUM [-Z-] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
 5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH. PARALLEL TO PRIMARY DATUM [-Z-] .

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.00	—	1.20
A1	0.25	—	0.35
øb	0.35	0.40	0.45
c	—	0.21	—
D	5.90	6.00	6.10
D1	4.70	4.80	4.90
E	5.90	6.00	6.10
E1	4.70	4.80	4.90
e	—	0.80	—
y	0.00	—	0.10

CUSTOMER :

APPROVED BY: *Sandy Sue* DATE: 03/05/'04

CHECK BY: *Ashburn Lee* DATE: 03/05/'04

APPROVAL: *Kevin Liao* DATE: 03/05/'04

APPROVAL: *Jack Tu* DATE: 03/05/'04

LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z
PRECISION IND., LTD. TAICHUNG., TAIWAN. R. O. C

TITLE:
**MINI BGA 49L(6x6mm) PACKAGE
OUTLINE DRAWING**

DWG. NO. PO-MBGA-013 REV. 2

UNIT : mm SCALE : 18/1 SHEET 1 OF 1